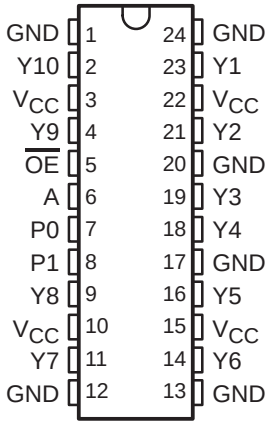
- **Controlled Baseline**
  - **One Assembly/Test Site, One Fabrication Site**
- **Extended Temperature Performance of −55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications**
- **Operates at 3.3-V V_{CC}**
- **LVTTL-Compatible Inputs and Outputs**
- **Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})**
- **Distributes One Clock Input to 10 Outputs**
- **Outputs Have Internal Series Damping Resistor to Reduce Transmission Line Effects**
- **Distributed V_{CC} and Ground Pins Reduce Switching Noise**
- **State-of-the-Art *EPIC*-II*B*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **Shrink Small-Outline (DB) Package**

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

DB PACKAGE
(TOP VIEW)



description

The CDC2351 is a high-performance clock-driver circuit that distributes one input (A) to 10 outputs (Y) with minimum skew for clock distribution. The output-enable ($\overline{OE}$) input disables the outputs to a high-impedance state. Each output has an internal series damping resistor to improve signal integrity at the load. The CDC2351 operates at nominal 3.3-V V_{CC}.

The propagation delays are adjusted at the factory using the P0 and P1 pins. The factory adjustments ensure that the part-to-part skew is minimized and is kept within a specified window. Pins P0 and P1 are not intended for customer use and should be connected to GND.

The CDC2351M is characterized for operation over the full military temperature range of −55°C to 125°C.

ORDERING INFORMATION

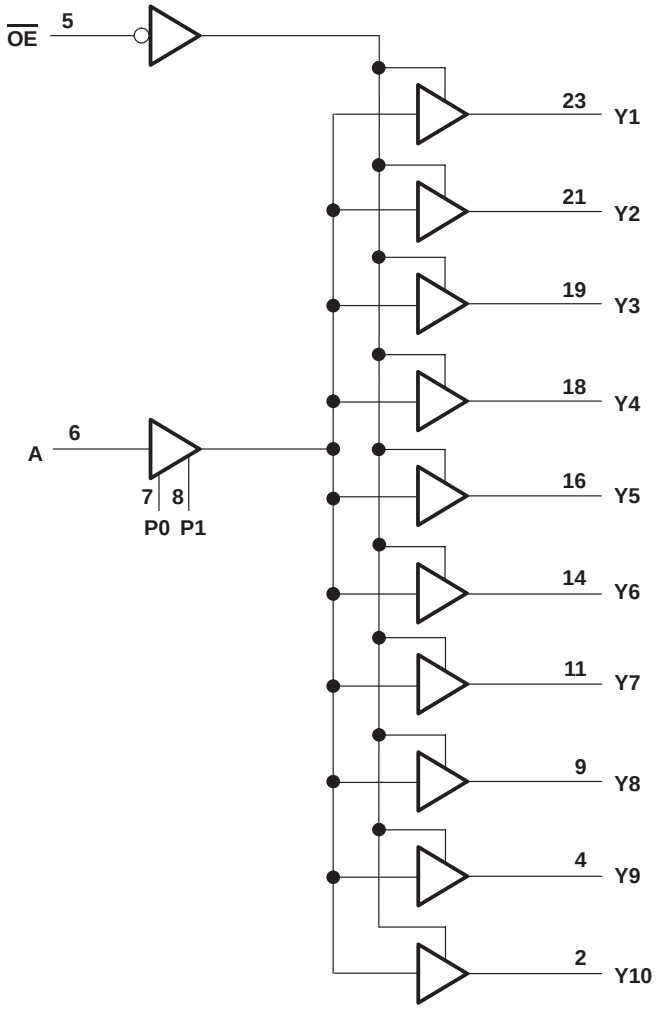
T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−55°C to 125°C	SSOP − DB	Tape and Reel	CDC2351MDBREP	CK2351MEP

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS		OUTPUTS
A	$\overline{OE}$	In
L	H	Z
H	H	Z
L	L	L
H	L	H

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 4.6 V
Input voltage range, V_I (see Note 1) . . . . . −0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state,
V_O (see Note 1) . . . . . −0.5 V to 3.6 V
Current into any output in the low state, I_O . . . . . 24 mA
Input clamp current, I_{IK} (V_I < 0) . . . . . −18 mA
Output clamp current, I_{OK} (V_I < 0) . . . . . −50 mA
Maximum power dissipation at T_A = 55°C (in still air) (see Note 2): DB package . . . . . 0.65 W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, see the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		3	3.6	V
V_{IH}	High-level input voltage		2		V
V_{IL}	Low-level input voltage			0.8	V
V_I	Input voltage		0	5.5	V
I_{OH}	High-level output current			−12	mA
I_{OL}	Low-level output current			12	mA
f_{clock}	Input clock frequency			100	MHz
T_A	Operating free-air temperature	CDC2351M	−55	125	°C

NOTE 3: Unused pins (input or I/O) must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			MIN	TYP	MAX	UNIT
V_{IK}	V_{CC} = 3 V,	I_I = −18 mA				−1.2	V
V_{OH}	V_{CC} = 3 V,	I_{OH} = − 12 mA		2			V
V_{OL}	V_{CC} = 3 V,	I_{OL} = 12 mA				0.8	V
I_I	V_{CC} = 3.6 V,	V_I = V_{CC} or GND				±1	μA
I_O‡	V_{CC} = 3.6 V,	V_O = 2.5 V		−7		−70	mA
I_{OZ}	V_{CC} = 3.6 V,	V_{CC} = 3 V or 0				±10	μA
I_{CC}	V_{CC} = 3.6 V,	I_O = 0, V_I = V_{CC} or GND	Outputs high			0.3	mA
			Outputs low			15	
			Outputs disabled			0.3	
C_i	V_I = V_{CC} or GND,	V_{CC} = 3.3 V,	f = 10 MHz		4		pF
C_o	V_O = V_{CC} or GND,	V_{CC} = 3.3 V,	f = 10 MHz		6		pF

‡ Not more than one output should be tested at a time and the duration of the test should not exceed one second.

switching characteristics, C_L = 50 pF (see Figure 1 and Figure 2)

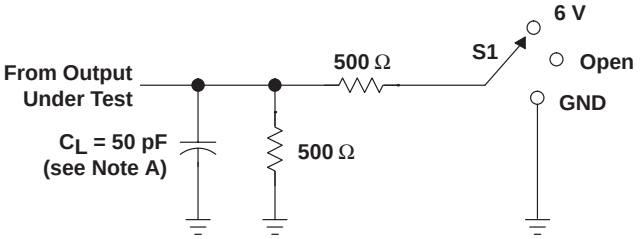
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 3.3 V, T_A = 25°C			V_{CC} = 3 V to 3.6 V, T_A = −55°C to 125°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
t_{PLH}	A	Y	3.8	4.3	4.8	1.1	11	ns
t_{PHL}			3.6	4.1	4.6	1	9.7	
t_{PZH}	$\overline{OE}$	Y	2.4	4.9	6	1	12	ns
t_{PZL}			2.4	4.3	6	1	11.1	
t_{PHZ}	$\overline{OE}$	Y	2.2	4.4	6.3	1	11.1	ns
t_{PLZ}			2.2	4.6	6.3	1	11.5	
$t_{sk(o)}$	A	Y		0.3	0.5		2.5	ns
$t_{sk(p)}$	A	Y		0.2	0.8		3	ns
$t_{sk(pr)}$	A	Y			1			ns
t_r	A	Y					2.5	ns
t_f	A	Y					2.5	ns

switching characteristics temperature and V_{CC} coefficients over recommended operating free-air temperature and V_{CC} range (see Note 4)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$\propto t_{PLH}(T)$	Average temperature coefficient of low-to-high propagation delay	A	Y		85†	ps/10°C
$\propto t_{PHL}(T)$	Average temperature coefficient of high-to-low propagation delay	A	Y		50†	ps/10°C
$\propto t_{PLH}(V_{CC})$	Average V_{CC} coefficient of low-to-high propagation delay	A	Y		−145‡	ps/ 100 mV
$\propto t_{PHL}(V_{CC})$	Average V_{CC} coefficient of high-to-low propagation delay	A	Y		−100‡	ps/ 100 mV

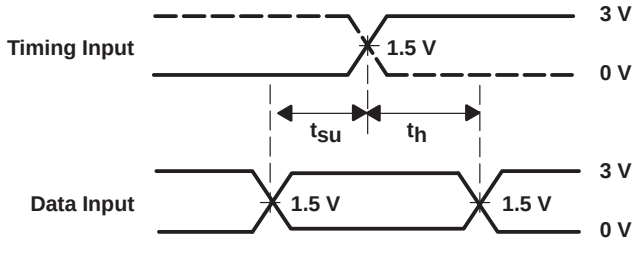
† $\propto t_{PLH}(T)$ and $\propto t_{PHL}(T)$ are virtually independent of V_{CC}.
‡ $\propto t_{PLH}(V_{CC})$ and $\propto t_{PHL}(V_{CC})$ are virtually independent of temperature.
NOTE 4: This data was extracted from characterization material and has not been tested at the factory.

PARAMETER MEASUREMENT INFORMATION

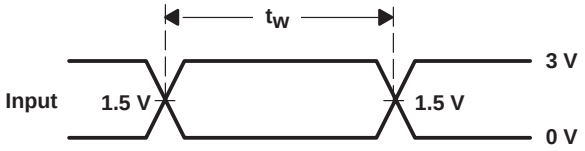


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



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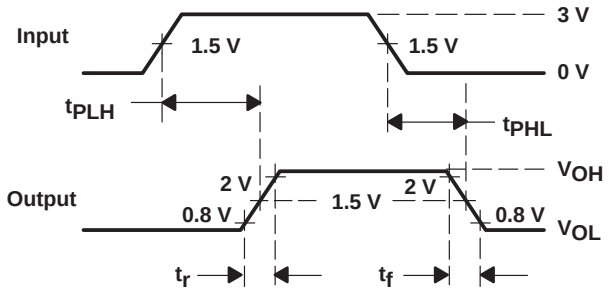
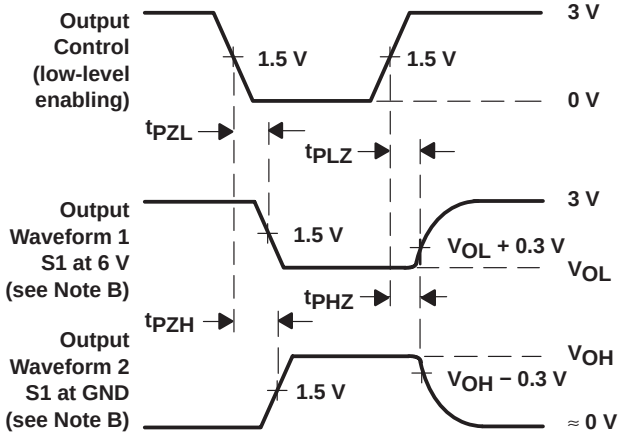


VOLTAGE WAVEFORMS

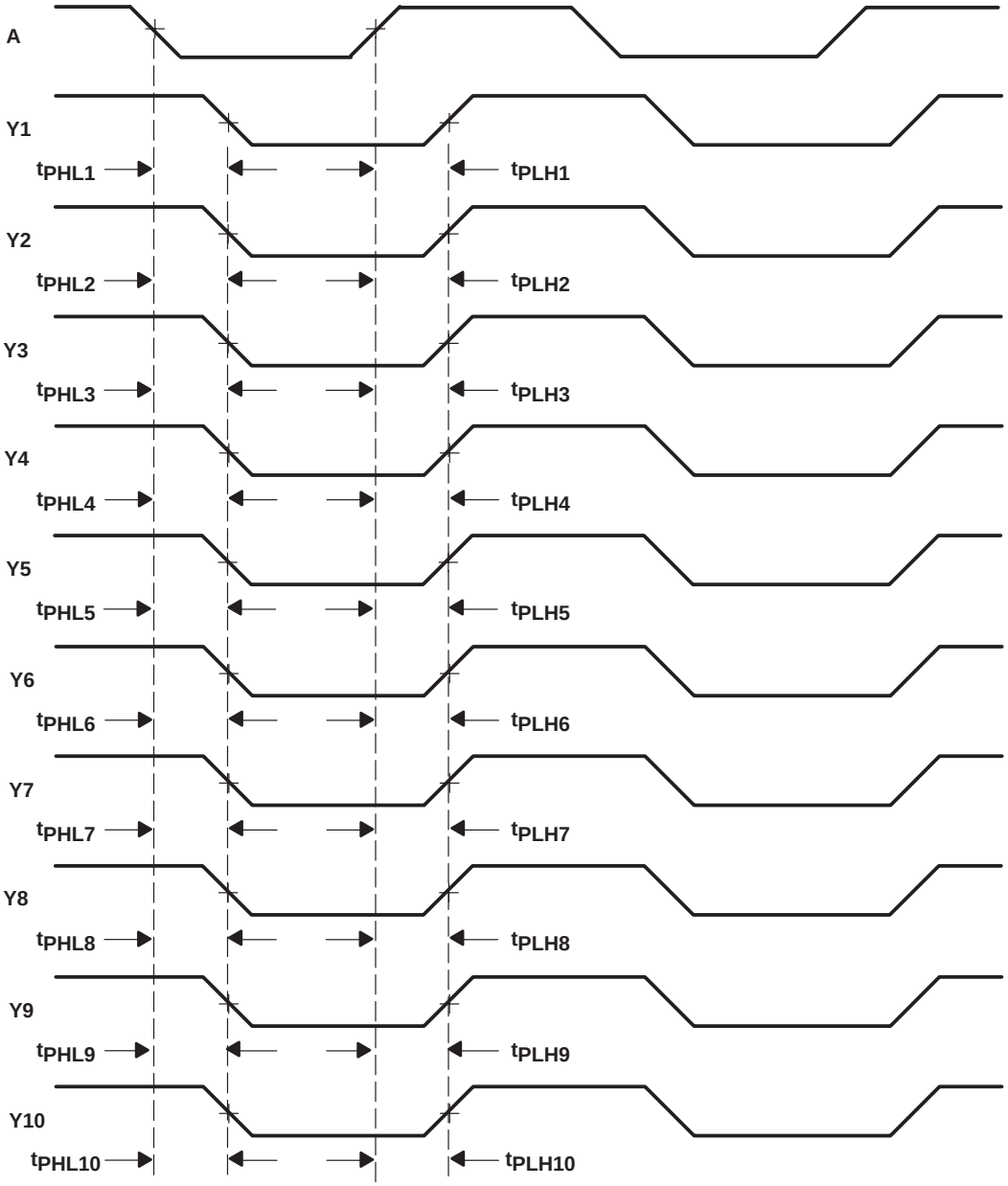


VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



NOTES: A. Output skew, $t_{sk(o)}$, is calculated as the greater of:
- The difference between the fastest and slowest of t_{PLHn} (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10)
- The difference between the fastest and slowest of t_{PHLn} (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10)

B. Pulse skew, $t_{sk(p)}$, is calculated as the greater of $| t_{PLHn} - t_{PHLn} |$ (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10).

C. Process skew, $t_{sk(pr)}$, is calculated as the greater of:
- The difference between the fastest and slowest of t_{PLHn} (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10) across multiple devices under identical operating conditions.
- The difference between the fastest and slowest of t_{PHLn} (n = 1, 2, 3, 4, 5, 6, 7, 8, 9, 10) across multiple devices under identical operating conditions.

Figure 2. Waveforms for Calculation of $t_{sk(o)}$, $t_{sk(p)}$, $t_{sk(pr)}$

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
CDC2351MDBREP	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CDC2351MDBREPG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
V62/04757-01XE	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

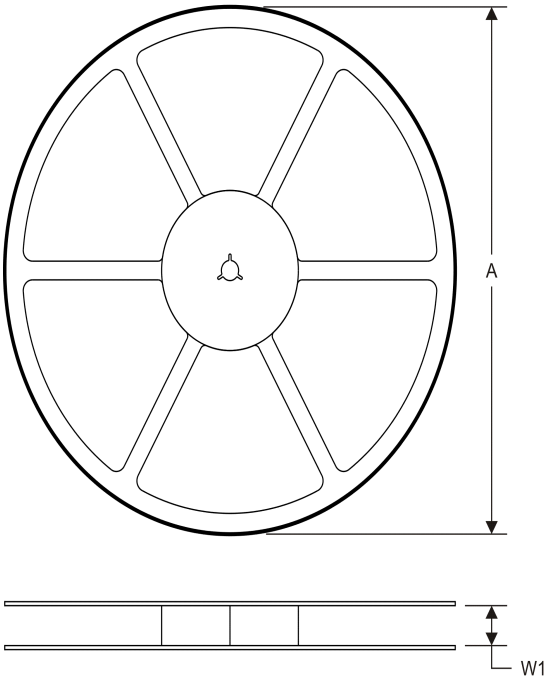
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

OTHER QUALIFIED VERSIONS OF CDC2351-EP :
- Catalog: CDC2351

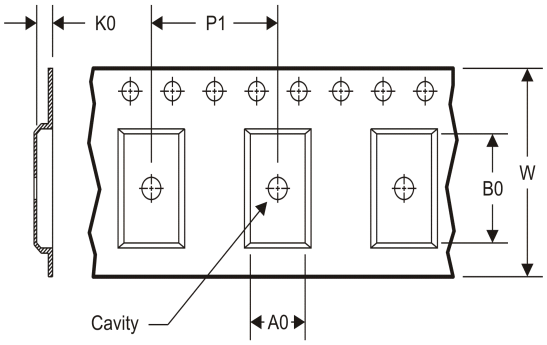
NOTE: Qualified Version Definitions:
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



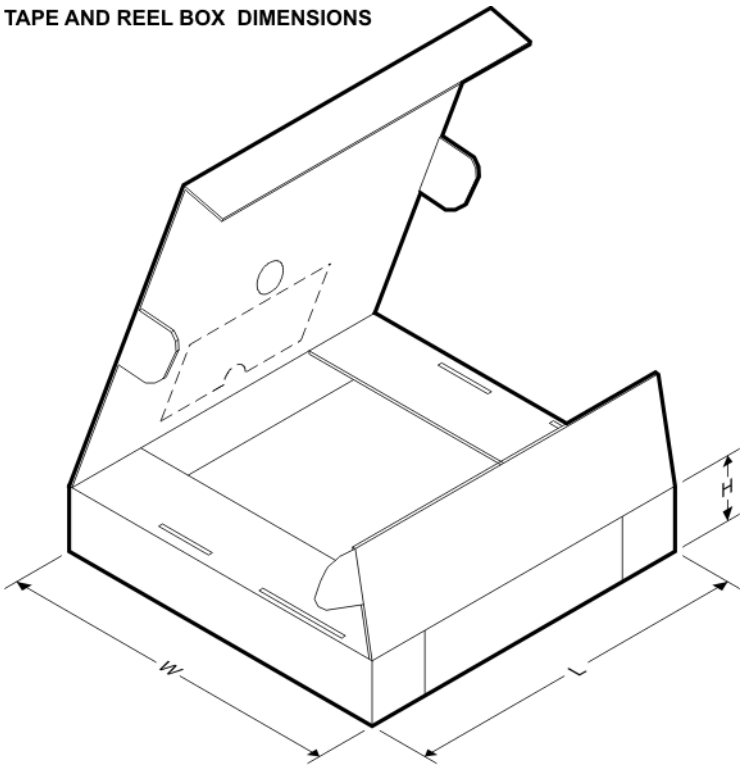
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC2351MDBREP	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC2351MDBREP	SSOP	DB	24	2000	367.0	367.0	38.0

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